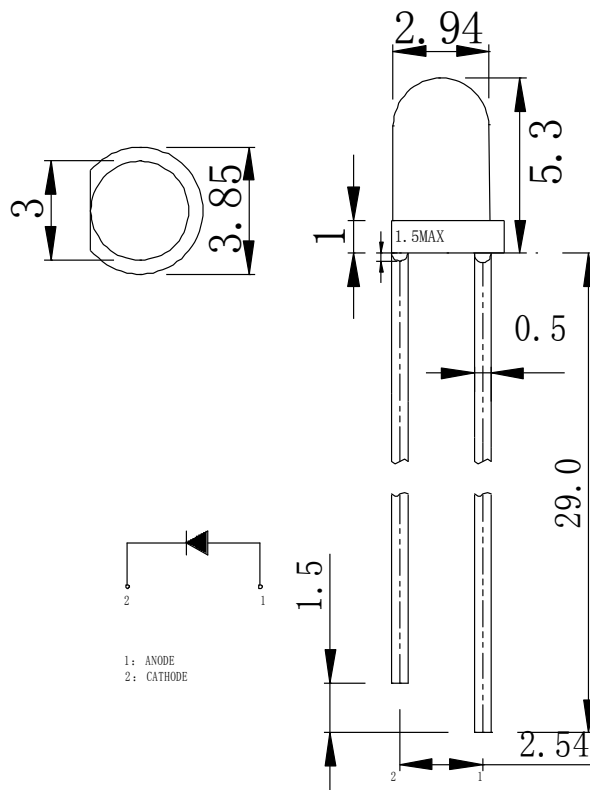


ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

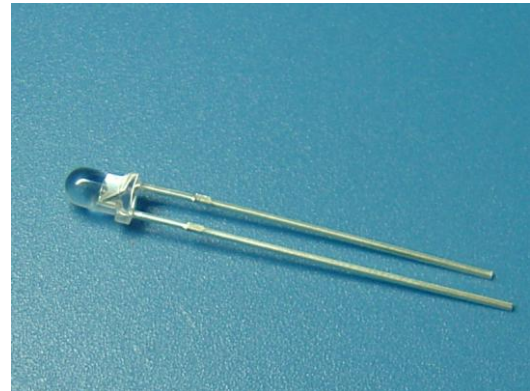
Features

- ϕ 3 LAMP LED.
- LOW POWER CONSUMPTION.
- CABINED VIEWING ANGLE.
- IDEAL FOR BACKLIGHT、LIGHTING AND INDICATOR.
- PACKAGE: 1000PCS / BAG.

Package Dimensions



HL-308H256WC-MD



Description

This devices are made with TS InGaN.

Tolerance Grade	Dimension Tolerance (UNIT:mm)			
	0.5~3	3~6	6~30	30~120
	± 0.1	± 0.2	± 0.3	± 0.5
Chip		Lens Color		
Material	Emitting Color	Water Clear		
InGaN	White			

■ Absolute Maximum Rating

Item	Symbol	Value	Unit
Forward Current	I_F	20	mA
Peak Forward Current*	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	80	mW
Electrostatic discharge	E_{SD}	1000	V
Operation Temperature	T_{opr}	-30~+80	°C
Storage Temperature	T_{stg}	-30~+80	°C
Lead Soldering Temperature*	T_{sol}	Max. 260°C for 5sec Max.	

* I_{FP} Conditions: Pulse Width $\leq 10\text{msec}$

* T_{sol} Conditions: 3mm from the base of the epoxy bulb

■ Typical Optical/ Electrical Characteristics $T_a=25^\circ\text{C}$

Item	Symbol	Condition	Rank	Min.	Typ.	Max.	Unit
Luminous Intensity	I_v	$I_F=20\text{mA}$	Z	6370		8280	mcd
			Z1	8280		10750	mcd
			Z2	10750		14000	mcd
Forward Voltage	V_F			2.8	3.2	3.6	V
Viewing Angle	$2\theta\ 1/2$			--	25	--	deg
Chromaticity coordinates	X			--	0.31	--	X:±0.015
	Y			--	0.32	--	Y:±0.025
Recommend Forward Current	$I_{F(\text{rec})}$	--		--	--	20	mA
Reverse Current	I_R	$V_r=5\text{V}$		--	--	10	uA

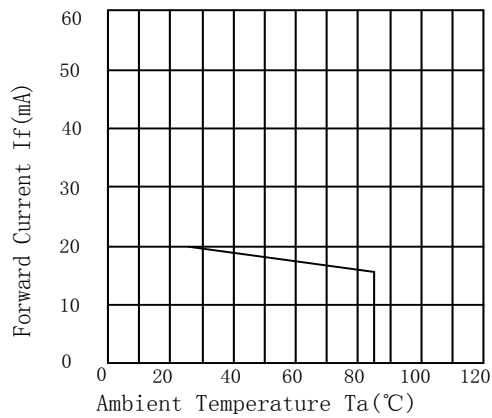
Notes:

Tolerance : $V_F \pm 0.1\text{V}$, $\lambda_d \pm 2\text{ nm}$, $I_V(\phi\text{ V}) \pm 15\%$, $2\theta\ 1/2 \pm 15\%$

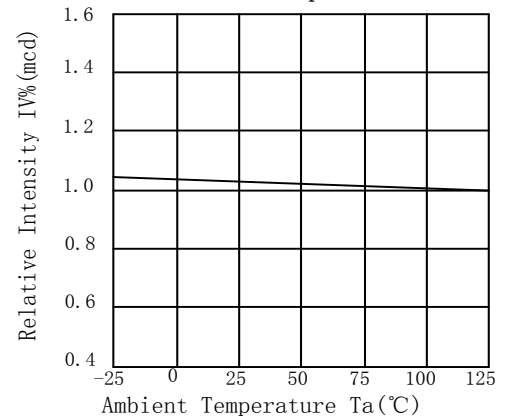
The above color coordinates measurement allowance tolerance ± 0.003



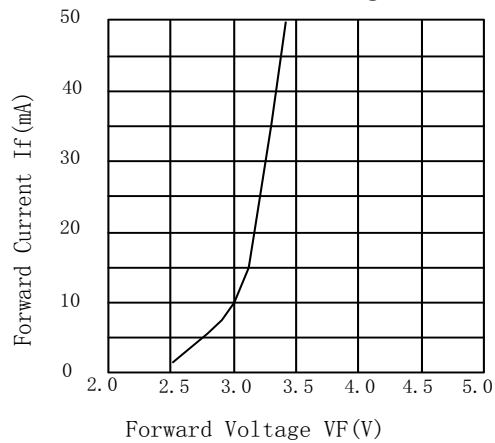
Forward Current vs.
Ambient Temperature



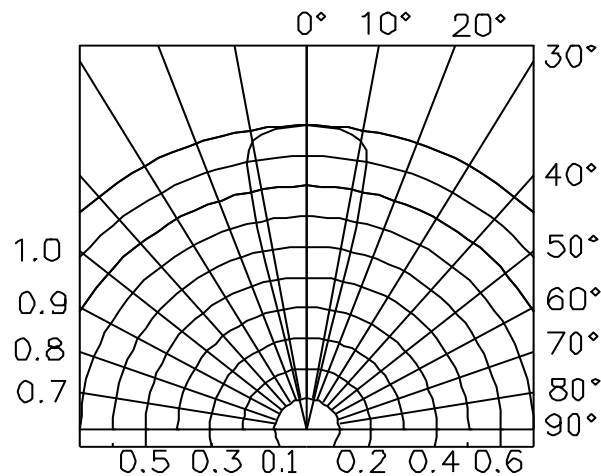
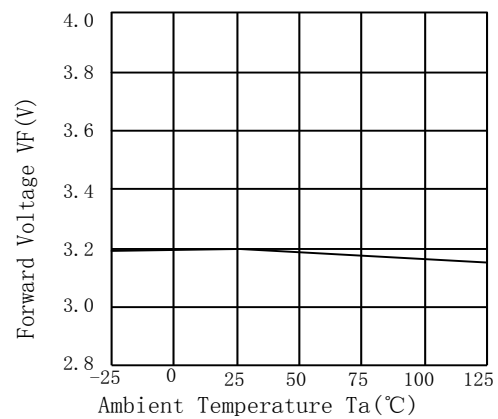
Relative Intensity vs.
Ambient Temperature

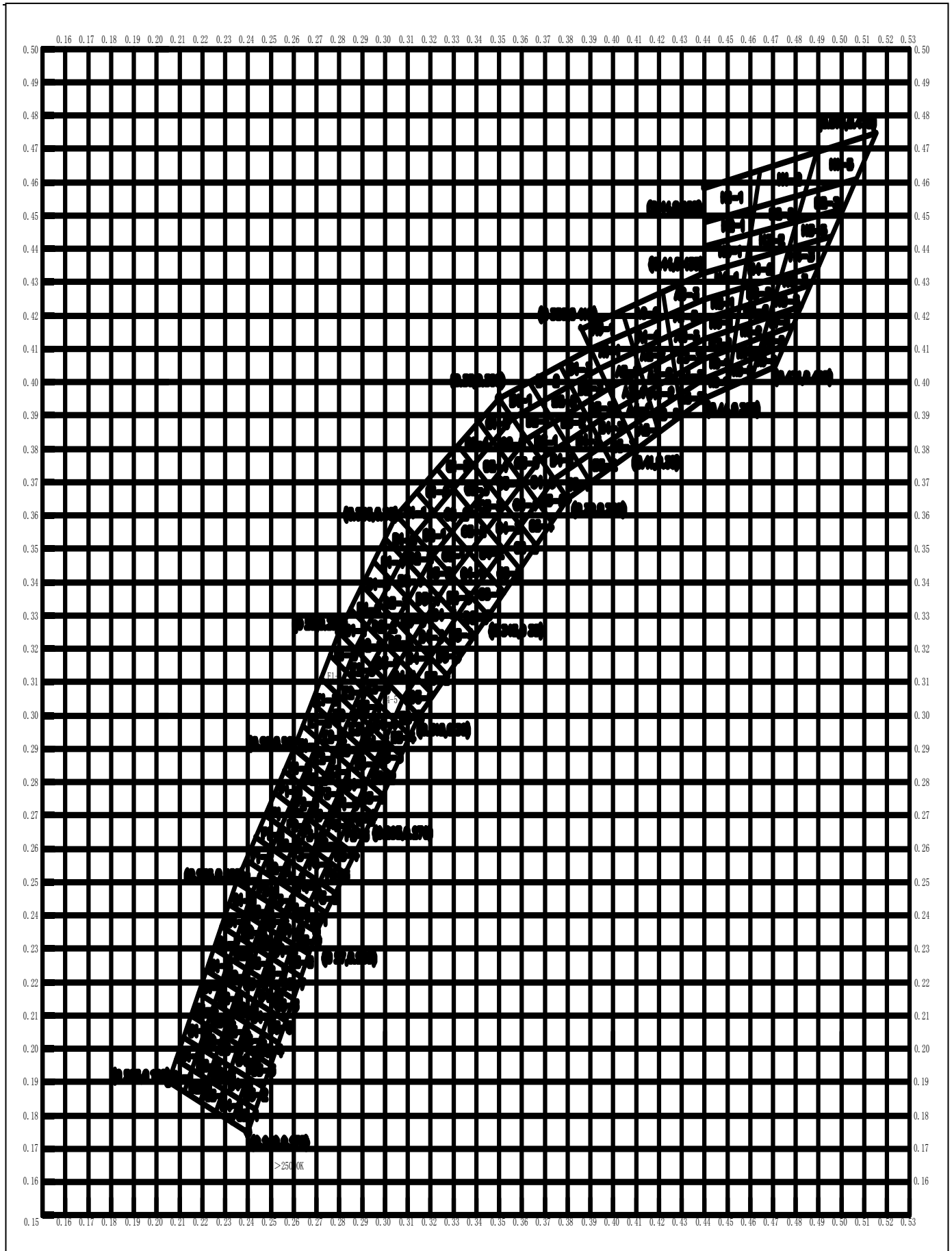


Forward Current vs.
Forward Voltage



Forward Voltage vs.
Ambient Temperature







Soldering:

1. Manual Of Soldering

The temperature of the iron tip should not be higher than 300°C and Soldering within 3 seconds per solder-land is to be observed.

2. DIP soldering (Wave Soldering):

Preheating: 120°C~150°C, within 120~180 sec.

Operation heating: 245°C ± 5°C within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).

